

WHAT IS CLAIMED IS:

1. A method for fast thickening electroforming stamper, in which a substrate is placed in an electroforming tank, the substrate having at least one processing face formed with a number of dented and projecting structures, a predetermined amount of electroforming bath being contained in the electroforming tank, a proper current being applied to the substrate and the electroforming bath at different electrodes, whereby through electroforming sedimentation, a first electroforming layer is formed on the processing face of the substrate, a face of the first electroforming layer adjacent to the processing face being formed as a mold face complementary to the dented and projecting structures of the processing face, a first thickening material being then connected with a face of the first electroforming layer distal from the substrate, the first thickening material, the first electroforming layer and the substrate together forming a combination body, the substrate being then separated from the first electroforming layer and the first electroforming layer and the first thickening material together forming a stamper.
2. The method for fast thickening electroforming stamper as claimed in claim 1, wherein the first electroforming layer has a thickness of about 1~2mm.
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3. The method for fast thickening electroforming stamper as

claimed in claim 1, wherein the surface of the first thickening material is previously roughed and then the first thickening material is adhered to the first electroforming layer by an adhesive.

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4. The method for fast thickening electroforming stamper as claimed in claim 1, wherein a welding agent is first painted over the surfaces of a first thickening material and the first electroforming layer and then the welding agent is heated to combine the first thickening material and the first electroforming layer together.
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5. The method for fast thickening electroforming stamper as claimed in claim 1, wherein the first thickening material is first leant on the first electroforming layer and then a laser beam is evenly projected onto the periphery of the first thickening material and the first electroforming layer so as to connect the first thickening material with the first electroforming layer.
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- 20 6. The method for fast thickening electroforming stamper as claimed in claim 5, wherein the diameter of the laser beam is within 0.2~0.6mm.
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7. The method for fast thickening electroforming stamper as claimed in claim 1, wherein after the first thickening material is connected with the first electroforming layer, a second electroforming layer being formed on one face of the first

thickening material distal from the first electroforming layer, the second electroforming layer, the first thickening material and the first electroforming layer together forming a metal layer, a second thickening material being connected with a face of the
5 metal layer distal from the first electroforming layer to form a stamper.

8. The method for fast thickening electroforming stamper as claimed in claim 7, wherein after the second electroforming
10 layer is formed, the substrate is separated from the first electroforming layer, whereby the second electroforming layer, the first thickening material and the first electroforming layer together form a metal layer.
- 15 9. The method for fast thickening electroforming stamper as claimed in claim 1, wherein after the first electroforming layer is formed on the surface of the substrate, the substrate is separated from the first electroforming layer.
- 20 10. The method for fast thickening electroforming stamper as claimed in claim 1, wherein a face of the first thickening material of the combination body distal from the first electroforming layer is connected with a second thickening material, after the substrate is separated from the first electroforming layer, the second electroforming layer, the first thickening material and the first electroforming layer together
25 forming a stamper.